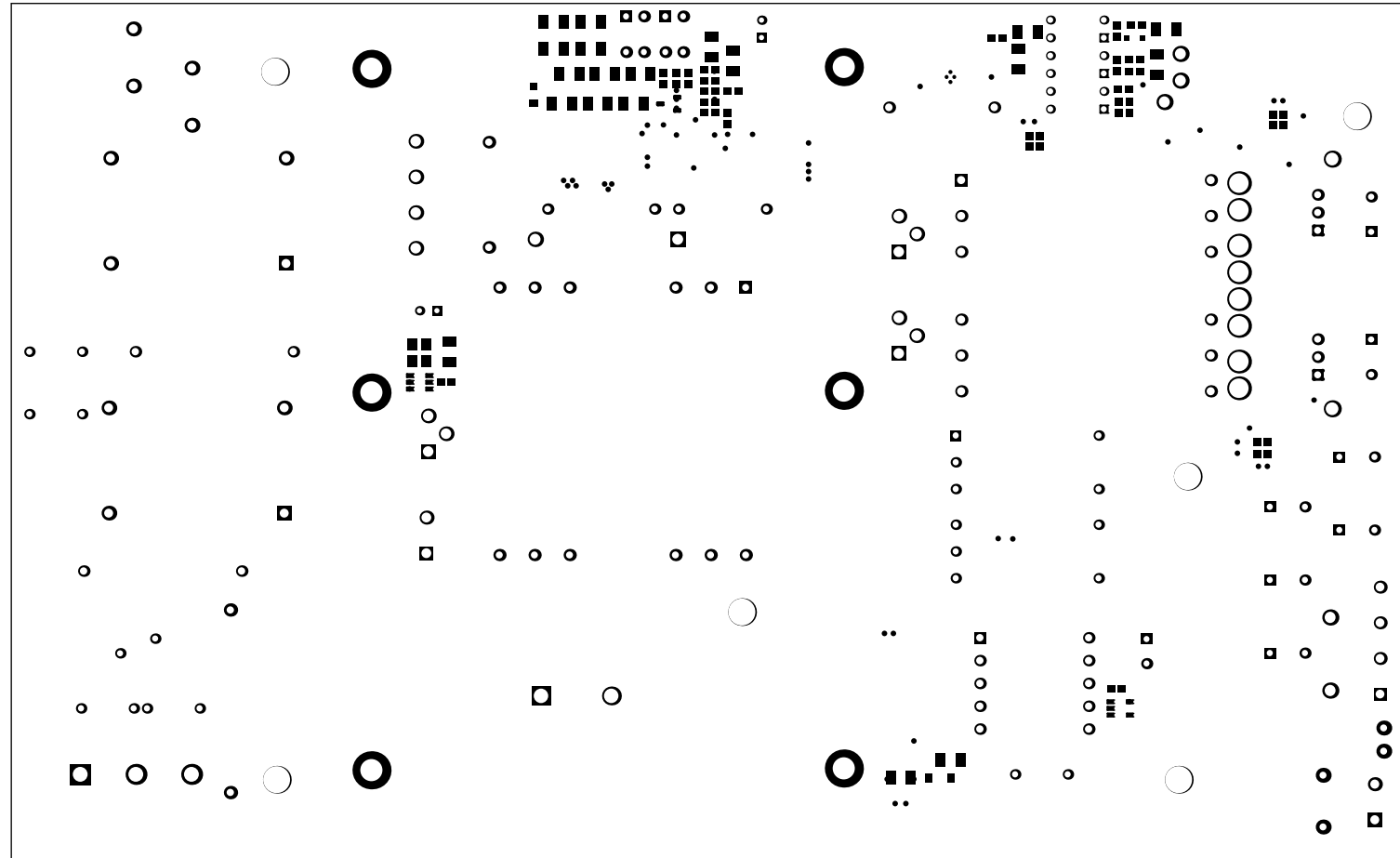
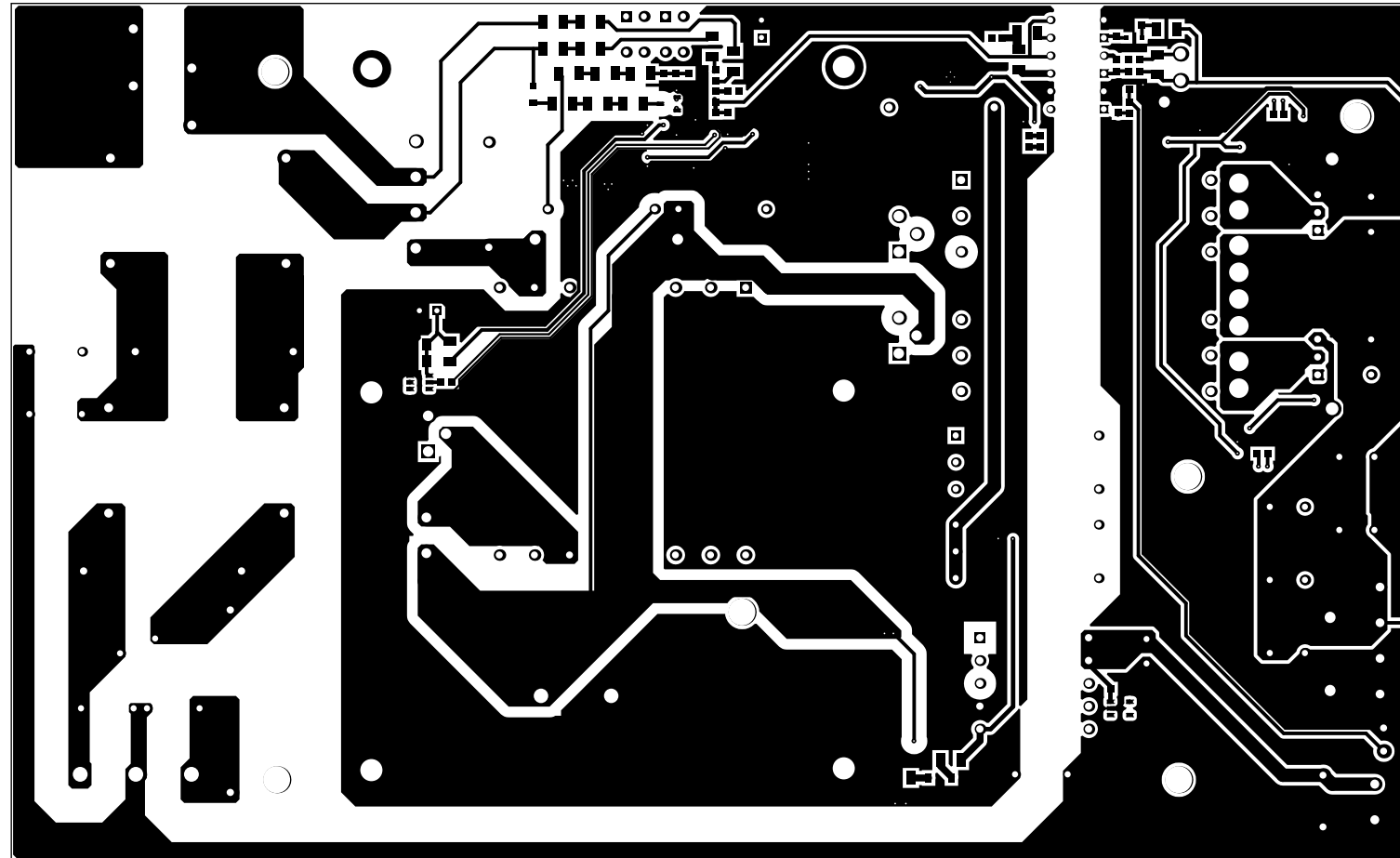


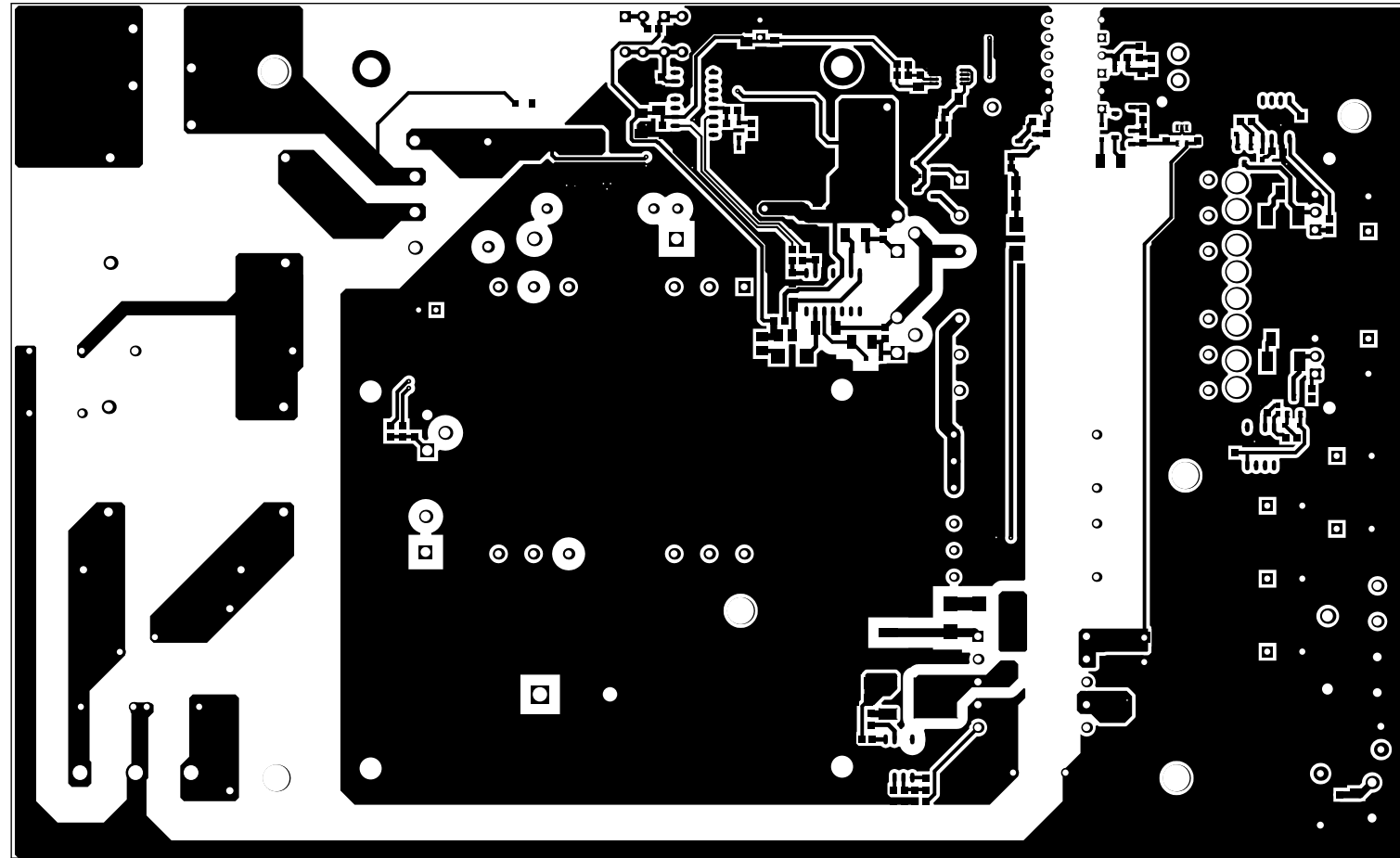
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11303	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Overlay	GENERATED : 11/2/2015	4:24:29 PM	TEXAS INSTRUMENTS



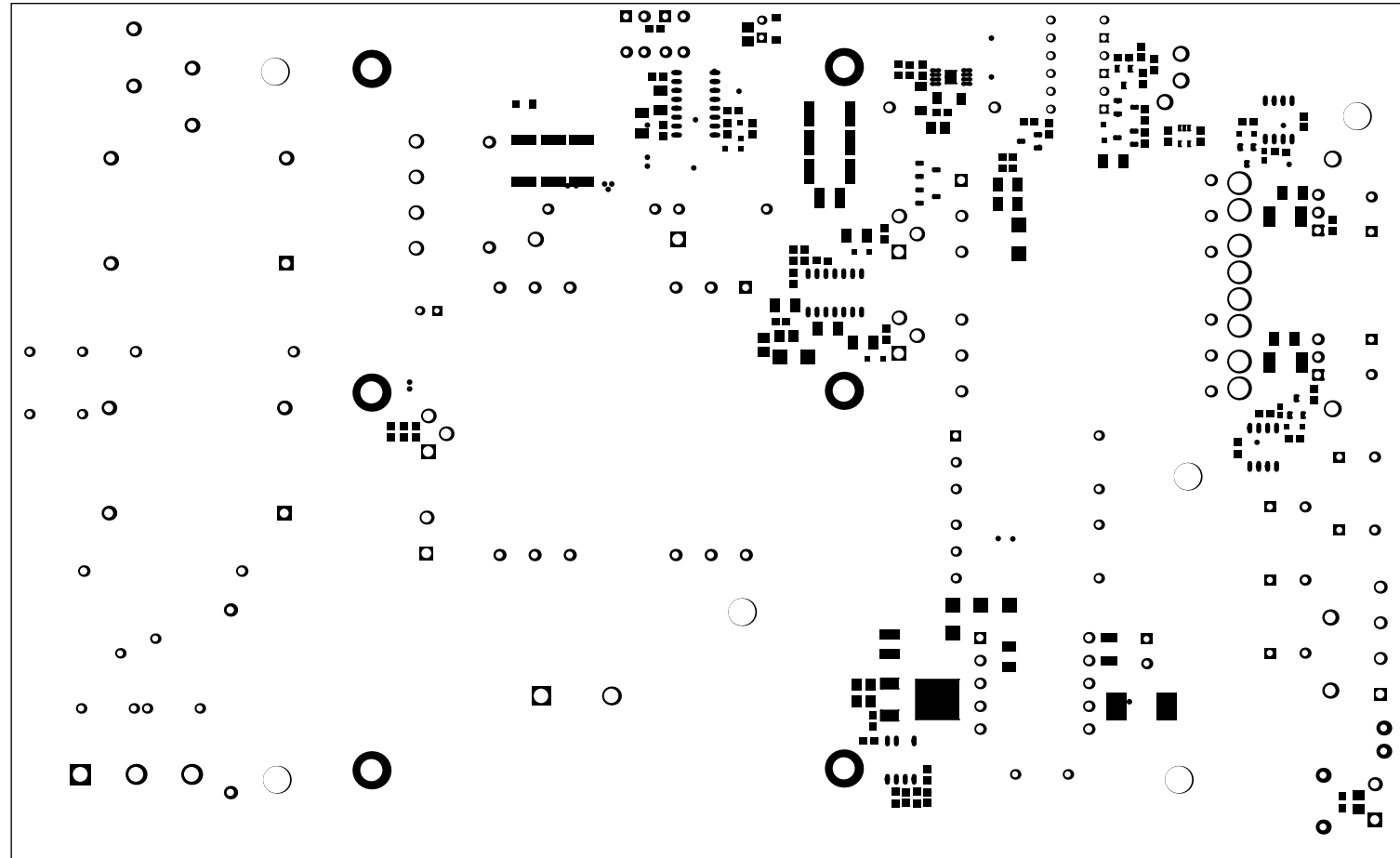
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11303	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask	GENERATED : 11/2/2015 4:24:30 PM	TEXAS INSTRUMENTS	



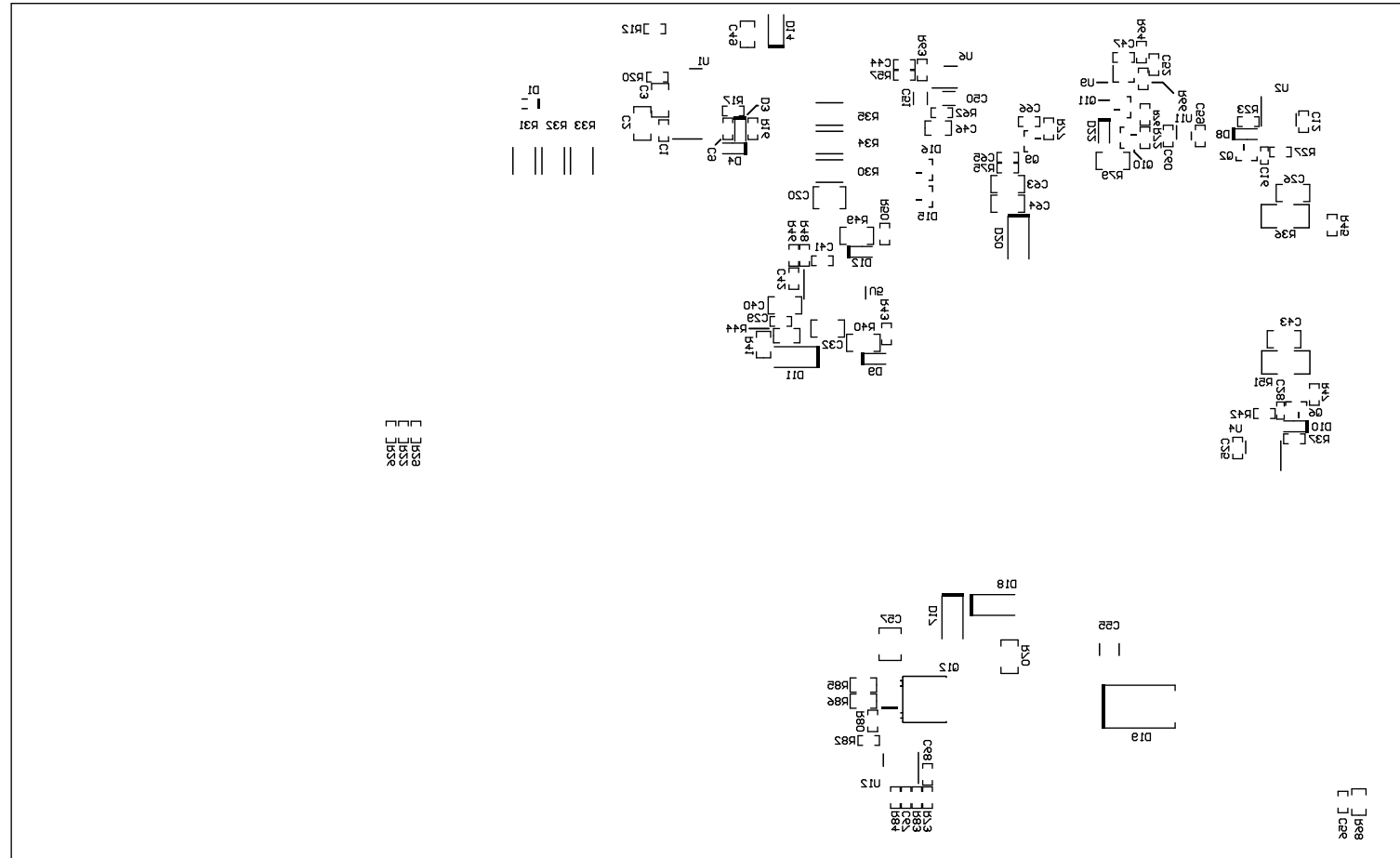
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11303	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 11/2/2015 4:24:31 PM	TEXAS INSTRUMENTS	



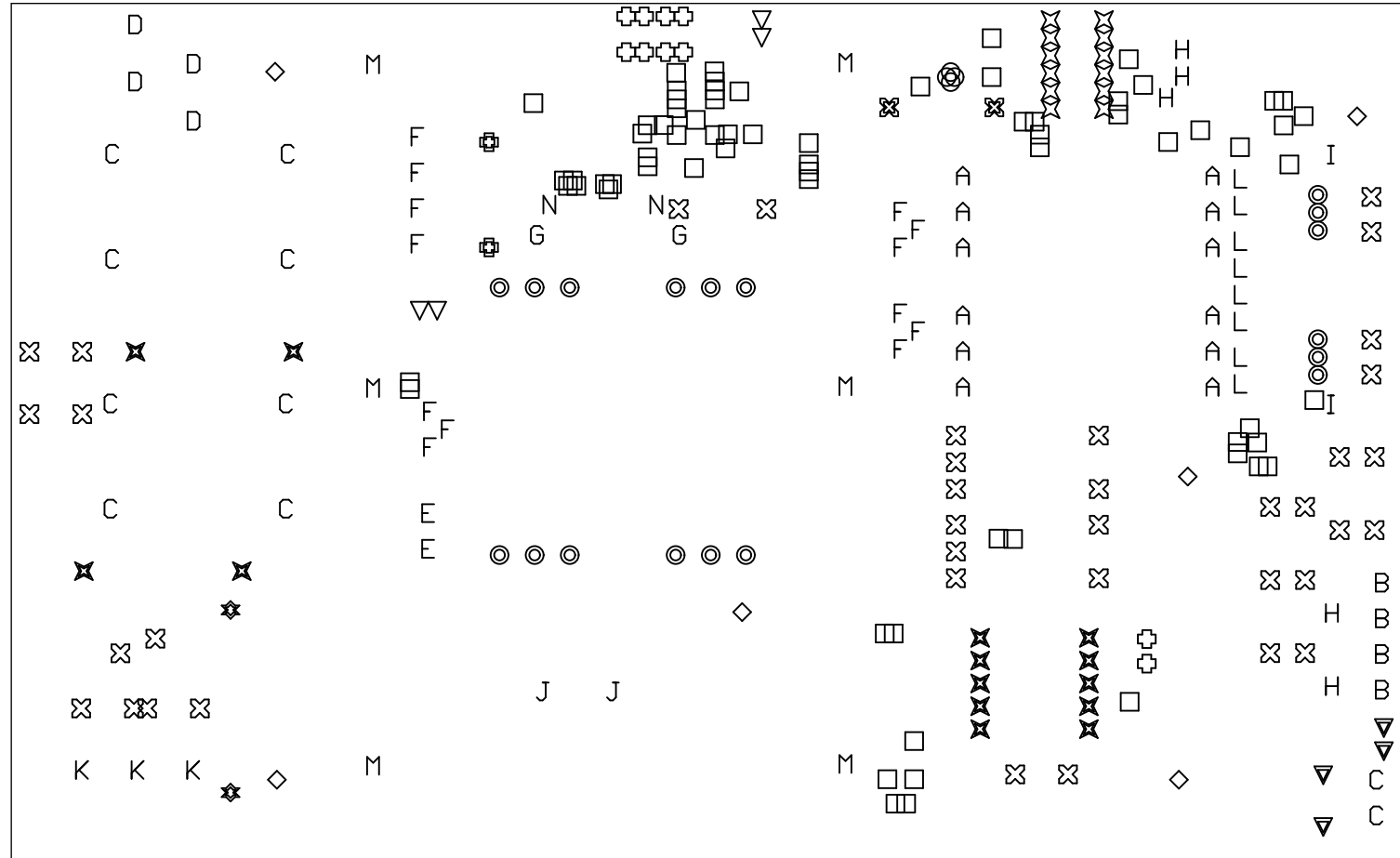
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11303	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 11/2/2015 4:24:32 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11303	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask	GENERATED : 11/2/2015 4:24:33 PM	TEXAS INSTRUMENTS	

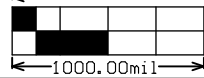
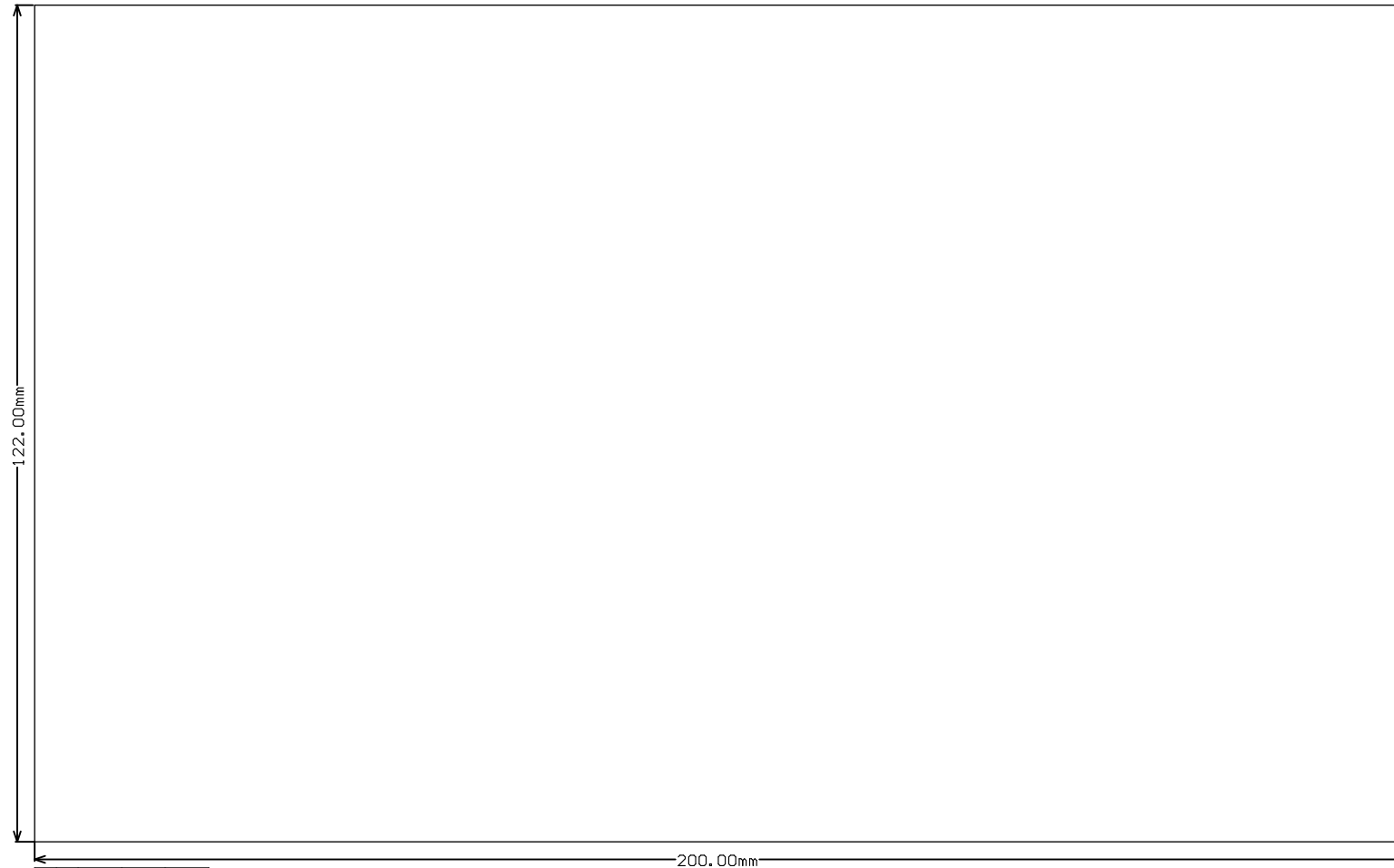


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11303	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Overlay	GENERATED : 11/2/2015 4:24:34 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
◇	6	152.00mil (3.861mm)	NPTH	Round
○	4	7.87mil (0.200mm)	PTH	Round
□	71	10.00mil (0.254mm)	PTH	Round
▽	4	29.53mil (0.750mm)	PTH	Round
⊗	12	33.46mil (0.850mm)	PTH	Round
⊙	10	35.00mil (0.889mm)	PTH	Round
⊗	38	35.43mil (0.900mm)	PTH	Round
N	2	37.00mil (0.940mm)	PTH	Round
●	18	39.37mil (1.000mm)	PTH	Round
▽	4	40.00mil (1.016mm)	PTH	Round
*	2	41.00mil (1.041mm)	PTH	Round
⊗	14	41.34mil (1.050mm)	PTH	Round
⊙	2	42.08mil (1.069mm)	PTH	Round
⊗	2	43.31mil (1.100mm)	PTH	Round
A	12	45.28mil (1.150mm)	PTH	Round
B	4	49.21mil (1.250mm)	PTH	Round
C	10	51.18mil (1.300mm)	PTH	Round
D	4	52.00mil (1.321mm)	PTH	Round
E	2	55.12mil (1.400mm)	PTH	Round
F	13	59.06mil (1.500mm)	PTH	Round
G	2	62.99mil (1.600mm)	PTH	Round
H	5	63.00mil (1.600mm)	PTH	Round
I	2	72.83mil (1.850mm)	PTH	Round
J	2	82.68mil (2.100mm)	PTH	Round
K	3	84.65mil (2.150mm)	PTH	Round
L	8	110.24mil (2.800mm)	PTH	Round
M	6	125.00mil (3.175mm)	PTH	Round
262 Total				

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11303	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing	GENERATED : 11/2/2015 4:24:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP11303	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:		
PLOT NAME = Board Dimensions	GENERATED : 11/2/2015	4:24:36 PM	TEXAS INSTRUMENTS

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